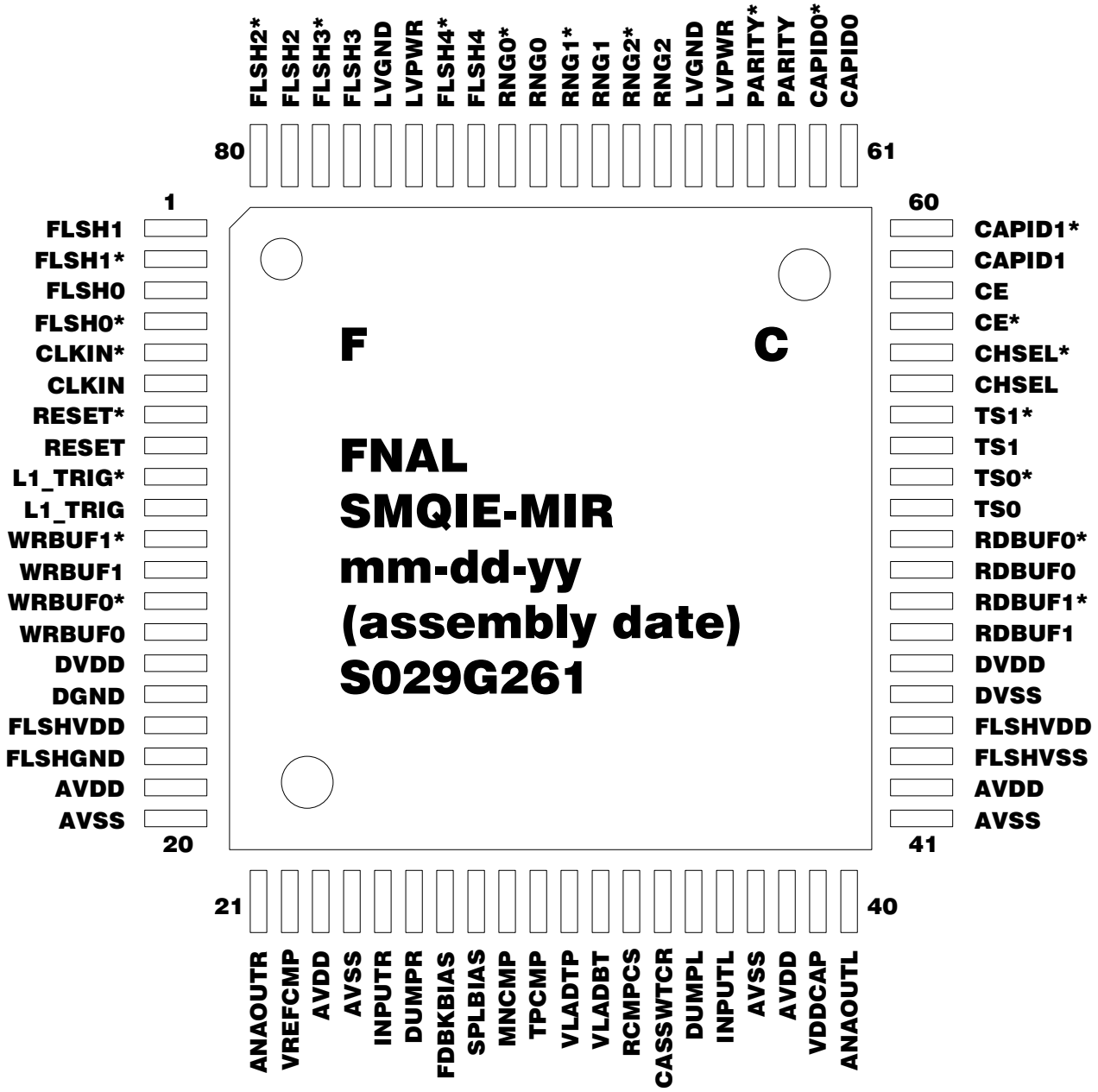
11/11/99

SMQIE-MIR

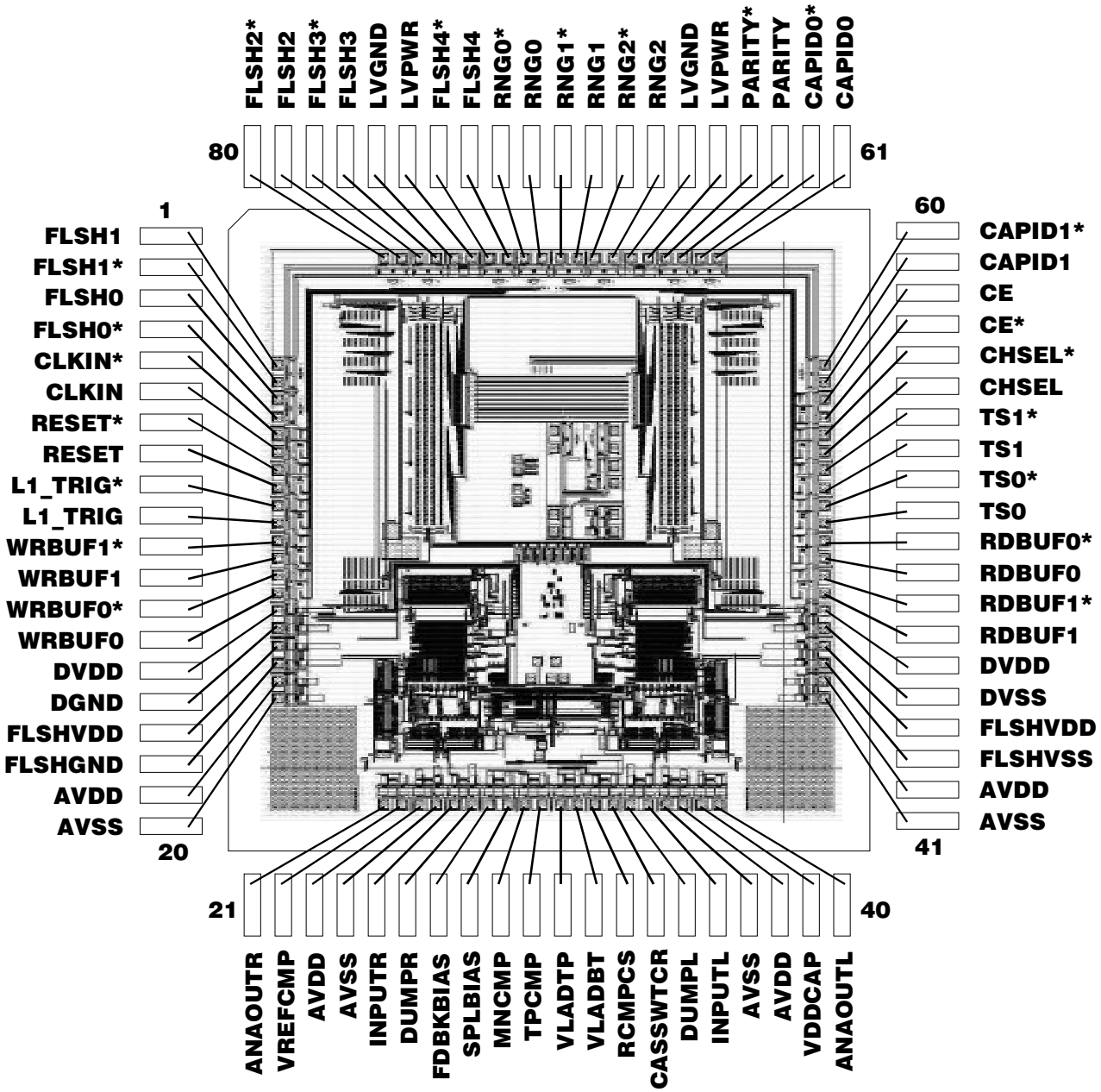
80-Lead TQFP Package Pin Assignments



07/15/99

SMQIE-MIR

80-Lead TQFP Package Bonding Diagram



SMQIE die size: 6.4032mm x 6.4032mm
Die bond pad size: 109.2 micrometers x 109.2 micrometers (Metal)
98.4 micrometers x 98.4 micrometers (Glass oxide opening)
Die bond pad pitch: 200.4 micrometers
Die bond pad metalization: Aluminum (1%Si, 1%Cu)
Die Attach: Thermally Conductive